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# *Use-it or Lose-it: Wearout and Lifetime in Future Chip-Multiprocessors*

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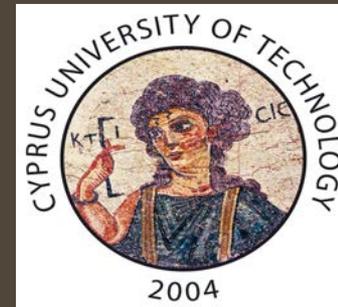
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# Chip-multiprocessor Wearout



ITRS: Rates of wearout induced failure to increase 10X in 10 years

- HCI and NBTI: transistor slowdown with use

Wearout effects in CMPs:

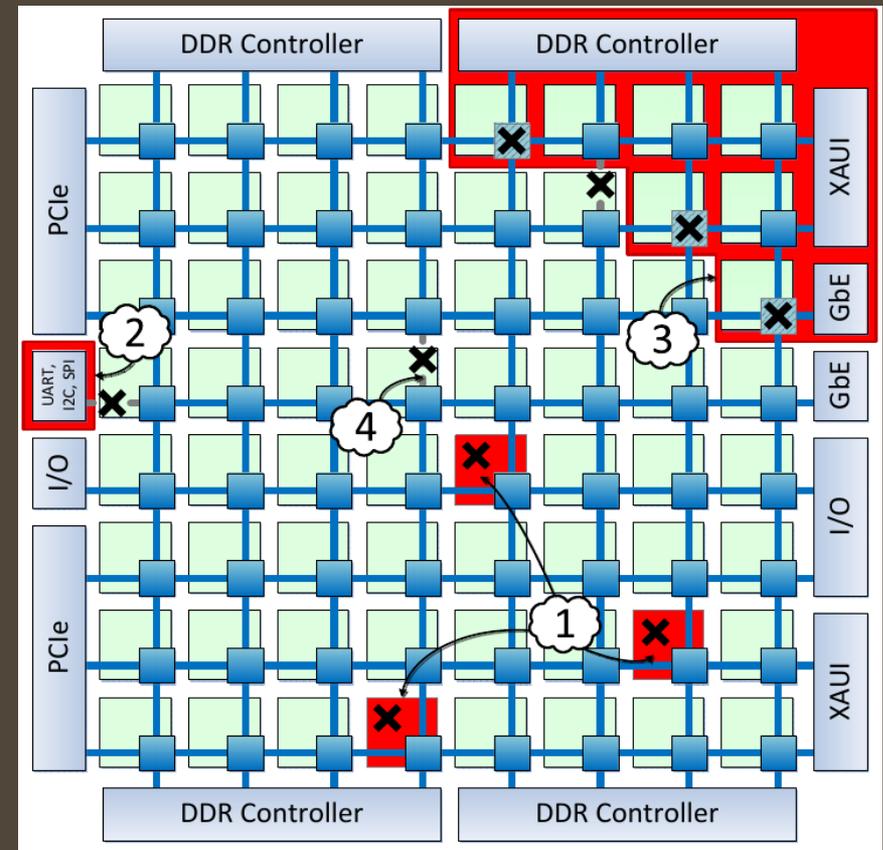
Recoverable failures:

- 1) Core failure
  - Failure detection and remapping

Non-recoverable failures:

- 2) I/O device disconnection
  - Device unreachable
- 3) Network partition
  - Disruption of communication between cores
- 4) Individual link breakage
  - Deadlock potential

Interconnect critical point of failure



A 64-core Chip-Multiprocessor (CMP) with various peripherals interconnected via a 2-D Mesh, all failure scenarios illustrated

# Use it or Lose it

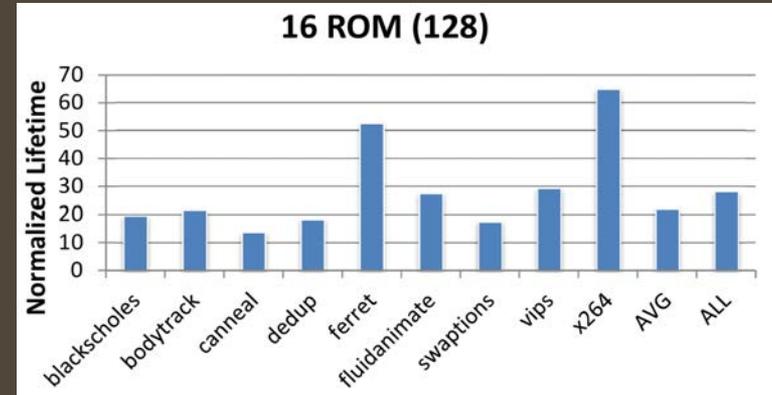


## Analysis of real CMP workloads:

- Low loads in interconnect
- NBTI causes critical path slowdown
- *Lack* of load leads to interconnect breakdown and failure

## The *Use it or Lose it*, wear-resistant router microarchitecture

- *Increases* utilization of router critical path
- **22x lifetime improvement!**



Lifetime improvement of 8x8 CMP executing applications from the PARSEC benchmark suite

Session 2B

(Alpha Gamma Rho Room)

4:00 PM today!